# 

# **3W Mono/Stereo BTL Audio Power Amplifiers** with Shutdown

# **General Description**

The MAX9710/MAX9711 are stereo/mono 3W bridge-tied

load (BTL) audio power amplifiers. These devices are

PC99/01 compliant, operate from a single 4.5V to 5.5V supply, and feature an industry-leading 100dB PSRR,

which allows these devices to operate from noisy sup-

plies without additional, costly power-supply conditioning. An ultra-low 0.005% THD+N ensures clean,

low-distortion amplification of the audio signal while

patented click-and-pop suppression eliminates audible transients on power and shutdown cycles. Power-saving

features include low 2mV Vos (minimizing DC current

drain through the speakers), low 7mA supply current, and a 0.5µA shutdown mode. A MUTE function allows

These devices include thermal overload protection, are

specified over the extended -40°C to +85°C temperature range, and are supplied in thermally efficient packages. The MAX9710 is available in either a 20-pin thin QFN package (5mm  $\times$  5mm  $\times$  0.8mm) or a 16-pin TSSOP-EP package. The MAX9711 is available in a 12-

the outputs to be quickly enabled or disabled.

pin thin QFN package (4mm × 4mm × 0.8mm).

### **Features**

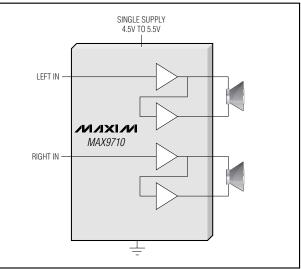
- ♦ 3W into 3Ω (1% THD+N)
- 4W into 3Ω (10% THD+N)
- Industry-Leading, Ultra-High 100dB PSRR
- PC99/01 Compliant
- Patented Click-and-Pop Suppression
- Low 0.005% THD+N
- Low Quiescent Current: 7mA
- Low-Power Shutdown Mode: 0.5µA
- MUTE Function
- Tiny 20-Pin Thin QFN (5mm × 5mm × 0.8mm) and 16-Pin TSSOP-EP Packages

# **Ordering Information**

PART	TEMP RANGE	PIN-PACKAGE	AMP
MAX9710 ETP	-40°C to +85°C	20-Thin QFN-EP*	Stereo
MAX9710EUE	-40°C to +85°C	16-TSSOP-EP*	Stereo
MAX9711 ETC	-40°C to +85°C	12-Thin QFN-EP*	Mono
*ED Expande	addla		

\*EP = Exposed paddle.

# Simplified Block Diagram



\_ Maxim Integrated Products 1

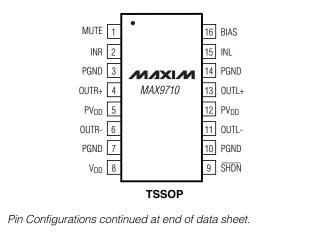
TOP VIEW

**Two-Way Radios** 

**Powered Speakers** 

General-Purpose Audio

**Applications** 



# 

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Flat-Panel TVs

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### **ABSOLUTE MAXIMUM RATINGS**

V <sub>DD</sub> to GND, PGND	+6V
PV <sub>DD</sub> to V <sub>DD</sub>	±0.3V
PGND to GND	±0.3V
All Other Pins to GND	0.3V to (V <sub>DD</sub> + 0.3V)
Continuous Input Current (into any pin	
except power supply and output pins).	±20mA
Continuous Power Dissipation ( $T_A = +70^{\circ}$	C)

12-Pin Thin QFN (derate 16.9mW/°C above +70°C) ....1349mW

16-Pin TSSOP-EP (derate 21.3mW/°C above +70°C)1702mW	1
20-Pin Thin QFN (derate 20.8mW/°C above +70°C)1667mW	1
Operating Temperature Range40°C to +85°C	
Storage Temperature Range65°C to +150°C	
Junction Temperature+150°C	
Lead Temperature (soldering, 10s)+300°C	

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

# **ELECTRICAL CHARACTERISTICS**

 $(V_{DD} = PV_{DD} = 5.0V, \text{ GND} = PGND = \text{MUTE} = 0V, V_{\overline{SHDN}} = 5V, R_{IN} = R_F = 15k\Omega, R_L = \infty$ . TA = T<sub>MIN</sub> to T<sub>MAX</sub>, unless otherwise noted. Typical values are at TA = +25°C.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS		MIN	ТҮР	МАХ	UNITS	
Supply Voltage Range	V <sub>DD</sub> /PV <sub>DD</sub>	Inferred from PSRR test		4.5		5.5	V	
Quiescent Supply Current		MAX9710 MAX9711			12	30		
(IVDD + IPVDD)	IDD				7	17	mA	
Shutdown Supply Current	ISHDN	SHDN = GND			0.5	30	μA	
Turn-On Time	ton	C <sub>BIAS</sub> = 1µF (10% of final value)			300		ms	
		$C_{BIAS} = 0.1 \mu F (10\% \text{ of final value})$			30			
Thermal Shutdown Threshold					160		°C	
Thermal Shutdown Hysteresis					15		°C	
OUTPUT AMPLIFIERS								
Output Offset Voltage	Vos	Vout_+ - Vout, Av =	= 2		±2	±14	mV	
			$V_{DD} = 4.5V$ to 5.5V	82	100		dB	
Power-Supply Rejection Ratio	PSRR	VRIPPLE = 200mVP-P (Note 2)	f = 1kHz		87			
			f = 20kHz		74			
Output Power	Роит	f <sub>IN</sub> = 1kHz, THD+N < 1%	$R_L = 8\Omega$	1.1	1.4		w	
			$R_L = 4\Omega$		2.6			
			$R_L = 3\Omega$		3			
Total Harmonic Distortion Plus	THD+N	f <sub>IN</sub> = 1kHz, BW =	$P_{OUT} = 1.2W, R_L = 8\Omega$		0.005		%	
Noise	IHD+N	22Hz to 22kHz	$P_{OUT} = 2W, 4\Omega$		0.01		%	
Signal-to-Noise Ratio	SNR	$R_L = 8\Omega$ , $V_{OUT} = 2.8V_{RMS}$ , BW = 22Hz to 22kHz			95		dB	
Slew Rate	SR				1.6		V/µs	
Maximum Capacitive Load Drive	CL	No sustained oscillations			1		nF	
Crosstalk		f <sub>IN</sub> = 10kHz			77		dB	
BIAS VOLTAGE (BIAS)								
BIAS Voltage	VBIAS			2.35	2.5	2.65	V	
Output Resistance	R <sub>BIAS</sub>				50		kΩ	
DIGITAL INPUTS (MUTE, SHDN	)							
Input Voltage High	VIH			2			V	
Input Voltage Low	VIL					0.8	V	
Input Leakage Current	lin					±1	μA	

**Note 1:** All devices are 100% production tested at +25°C. All temperature limits are guaranteed by design.

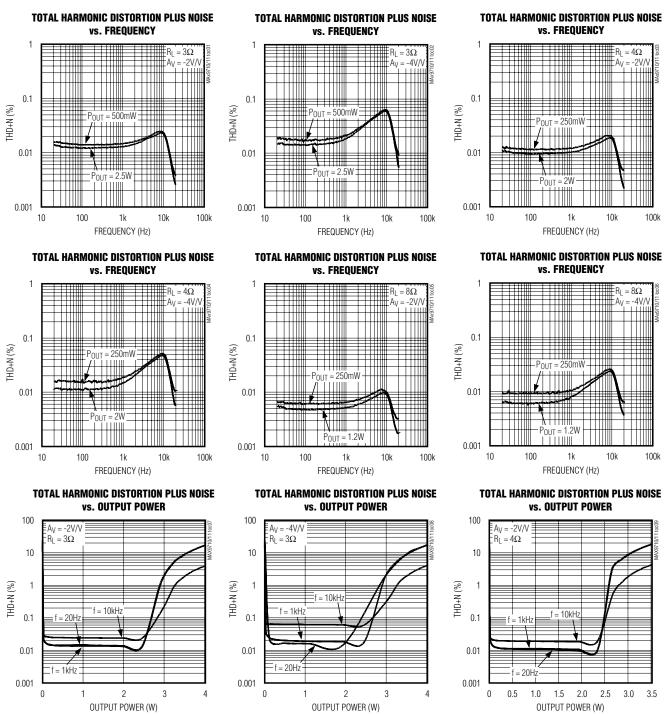
Note 2: PSSR is specified with the amplifier inputs connected to GND through  $\mathsf{R}_{\mathsf{IN}}$  and  $\mathsf{C}_{\mathsf{IN}}.$ 



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# **Typical Operating Characteristics**

(V<sub>DD</sub> = 5V, THD+N measurement bandwidth = 22Hz to 22kHz,  $T_A$  = +25°C, unless otherwise noted.)



MAX9710/MAX9711

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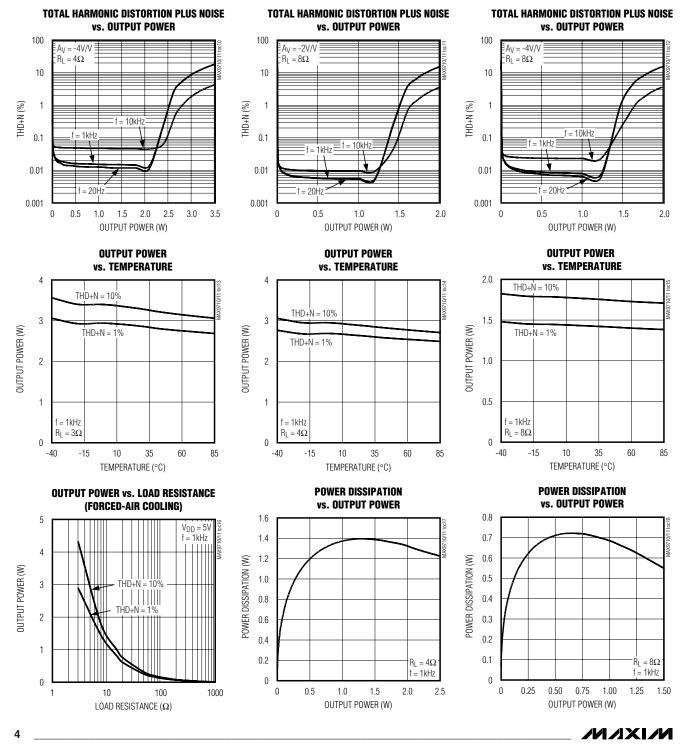
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M/IXI/N

# MAX9710/MAX971

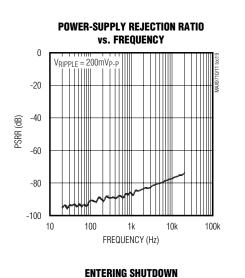


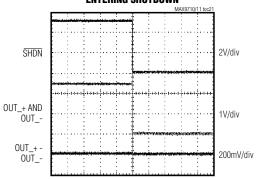
(V<sub>DD</sub> = 5V, THD+N measurement bandwidth = 22Hz to 22kHz,  $T_A = +25^{\circ}C$ , unless otherwise noted.)



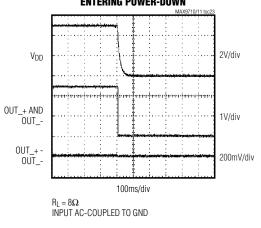
# **Typical Operating Characteristics (continued)**

 $(V_{DD} = 5V, THD+N \text{ measurement bandwidth} = 22Hz \text{ to } 22kHz, T_A = +25^{\circ}C, \text{ unless otherwise noted.})$ 

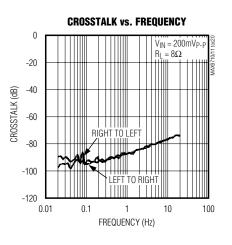




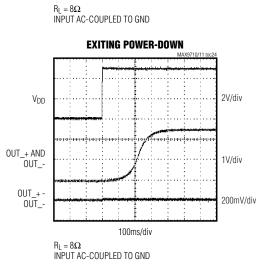








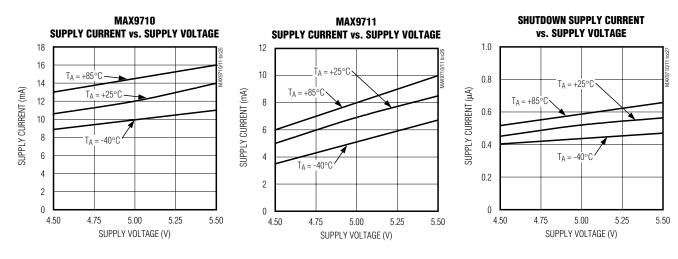
SHDN OUT\_+ AND OUT\_+ OUT\_+ -OUT\_+ OUT\_- -DUT\_- -D





# Typical Operating Characteristics (continued)

(V<sub>DD</sub> = 5V, THD+N measurement bandwidth = 22Hz to 22kHz,  $T_A$  = +25°C, unless otherwise noted.)



# **Pin Description**

PIN				
MAX9710 MAX9711		NAME	FUNCTION	
20-PIN QFN	16-PIN TSSOP	12-PIN QFN		
1	15		INL	Left-Channel Input
2	16	7	BIAS	DC Bias Bypass. See <i>BIAS Capacitor Selection</i> section for capacitor selection.
3, 10, 13, 16	—		N.C.	No Connection. Not internally connected.
4	1	9	MUTE	Active-High Mute Input
5	2		INR	Right-Channel Input
6, 11, 15, 20	3, 7, 10, 14	1, 3	PGND	Power Ground
7	4	_	OUTR+	Right-Channel Bridged Amplifier Positive Output
8, 18	5, 12	5, 11	PVDD	Output Amplifier Power Supply
9	6		OUTR-	Right-Channel Bridged Amplifier Negative Output
12	8	8	V <sub>DD</sub>	Power Supply
14	9	10	SHDN	Active-Low Shutdown. Connect SHDN to VDD for normal operation.
17	11	—	OUTL-	Left-Channel Bridged Amplifier Negative Output
19	13	_	OUTL+	Left-Channel Bridged Amplifier Positive Output
	—	2	IN	Amplifier Input
	_	6	GND	Ground
	—	12	OUT-	Bridged Amplifier Negative Output
	_	4	OUT+	Bridged Amplifier Positive Output
	_		EP	Exposed Pad. Connect to ground plane.

# **Detailed Description**

The MAX9710/MAX9711 are 3W BTL speaker amplifiers. The MAX9710 is a stereo speaker amplifier, while the MAX9711 is a mono speaker amplifier. Both devices feature a low-power shutdown mode, MUTE mode, and comprehensive click-and-pop suppression. These devices consist of high output-current op amps configured as BTL amplifiers (see *Functional Diagram*). The device gain is set by RF and RIN.

### BIAS

These devices operate from a single 5V supply and feature an internally generated, power-supply-independent, common-mode bias voltage of 2.5V referenced to ground. BIAS provides both click-and-pop suppression and sets the DC bias level for the audio outputs. BIAS is internally connected to the noninverting input of each speaker amplifier (see *Functional Diagram*). Choose the value of the bypass capacitor as described in the *BIAS Capacitor* section. No external load should be applied to BIAS. Any load lowers the BIAS voltage, affecting the overall performance of the device.

 $\label{eq:spectral} \begin{array}{c} \textbf{Shutdown} \\ \text{The MAX9710/MAX9711 feature a 0.5µA low-power shutdown mode that reduces quiescent current consumption. Pulling SHDN low disables the device's bias circuitry, the amplifier outputs are actively pulled low, and BIAS is driven to GND. Connect SHDN to V_DD for normal operation. \end{array}$ 

### MUTE

Both devices feature a clickless/popless MUTE mode. When the device is muted, the input disconnects from the amplifier. MUTE only affects the power amplifiers and does not shut down the device. Drive MUTE high to mute the device. Drive MUTE low for normal operation.

### **Click-and-Pop Suppression**

The MAX9710/MAX9711 feature Maxim's patented comprehensive click-and-pop suppression. During startup, the common-mode bias voltage of the amplifiers slowly ramps to the DC bias point using an S-shaped waveform. When entering shutdown, the amplifier outputs are actively driven low simultaneously. This scheme minimizes the energy present in the audio band.

For optimum click-and-pop suppression, choose:

RIN X CIN < RBIAS X CBIAS

where  $R_{BIAS} = 50 k\Omega$ .



+1 -1 VOUT(P-P) 2 x VOUT(P-P) VOUT(P-P) VOUT(P-P)

Figure 1. Bridge-Tied Load Configuration

# Applications Information

### **BTL Amplifier**

The MAX9710/MAX9711 are designed to drive a load differentially, a configuration referred to as BTL. The BTL configuration (Figure 1) offers advantages over the single-ended configuration, where one side of the load is connected to ground. Driving the load differentially doubles the output voltage compared to a single-ended amplifier under similar conditions. Thus, the differential gain of the device is twice the closed-loop gain of the input amplifier. The effective gain is given by:

$$A_{VD} = 2 \times \frac{R_F}{R_{IN}}$$

Substituting  $2 \times V_{OUT(P-P)}$  for  $V_{OUT(P-P)}$  into the following equations yields four times the output power due to doubling of the output voltage:

$$V_{RMS} = \frac{V_{OUT(P-P)}}{2\sqrt{2}}$$
$$P_{OUT} = \frac{V_{RMS}^{2}}{R_{I}}$$

Since the differential outputs are biased at midsupply, there is no net DC voltage across the load. This eliminates the need for DC-blocking capacitors required for single-ended amplifiers. These capacitors can be large, expensive, consume board space, and degrade low-frequency performance.

### **Power Dissipation and Heat Sinking**

Under normal operating conditions, the MAX9710/ MAX9711 dissipate a significant amount of power. The maximum power dissipation for each package is given in the *Absolute Maximum Ratings* section under Continuous Power Dissipation or can be calculated by the following equation:

$$P_{\text{DISSPKG}(\text{MAX})} = \frac{T_{\text{J}(\text{MAX})} - T_{\text{A}}}{\theta_{\text{J}\text{A}}}$$

where  $T_{J(MAX)}$  is +150°C,  $T_A$  is the ambient temperature, and  $\theta_{JA}$  is the reciprocal of the derating factor in °C/W as specified in the *Absolute Maximum Ratings* section. For example,  $\theta_{JA}$  of the 20-pin thin QFN package is 48.1°C/W.

The increase in power delivered by the BTL configuration directly results in an increase in internal power dissipation over the single-ended configuration. The maximum power dissipation for a given  $V_{DD}$  and load is given by the following equation:

$$P_{\text{DISS}(\text{MAX})} = \frac{2V_{\text{DD}}^2}{\pi^2 R_{\text{I}}}$$

If the power dissipation for a given application exceeds the maximum allowed for a given package, either reduce  $V_{DD}$ , increase load impedance, decrease the ambient temperature, or add heat sinking to the device (see *Layout and Grounding* section). Large output, supply, and ground PC board traces improve the maximum power dissipation in the package.

Thermal-overload protection limits total power dissipation in the MAX9710/MAX9711. When the junction temperature exceeds +160°C, the thermal protection circuitry disables the amplifier output stage. The amplifiers are enabled once the junction temperature cools by 15°C. A pulsing output under continuous thermal-overload conditions results as the device heats and cools.

### **Component Selection**

### Gain-Setting Resistors

External feedback components set the gain of both devices. Resistors  $R_F$  and  $R_{IN}$  (*Functional Diagram*) set the gain of the amplifier as follows:

$$A_{VD} = 2 \times \frac{R_F}{R_{IN}}$$

Input Filter

The input capacitor (C<sub>IN</sub>), in conjunction with  $\dot{R}_{IN}$ , forms a highpass filter that removes the DC bias from an incoming signal. The AC-coupling capacitor allows the amplifier to bias the signal to an optimum DC level. Assuming zero-source impedance, the -3dB point of the highpass filter is given by:

$$f_{-3dB} = \frac{1}{2\pi R_{IN}C_{IN}}$$

For optimum click-and-pop suppression, choose:

where  $R_{BIAS} = 50 k\Omega$ .

Setting f<sub>-3dB</sub> too high affects the low-frequency response of the amplifier. Use capacitors with dielectrics that have low-voltage coefficients, such as tantalum or aluminum electrolytic. Capacitors with high-voltage coefficients, such as ceramics, may result in an increase of distortion at low frequencies.

### **BIAS Capacitor**

BIAS is the output of the internally generated 2.5VDC bias voltage. The BIAS bypass capacitor, C<sub>BIAS</sub>, improves PSRR and THD+N by reducing power supply and other noise sources at the common-mode bias node, and also generates the clickless/popless startup DC bias waveform for the speaker amplifiers. Bypass BIAS with a 1µF capacitor to GND. Smaller values of C<sub>BIAS</sub> produce faster t<sub>ON</sub>/t<sub>OFF</sub> times but may result in increased click/pop levels.

### Supply Bypassing

Proper power-supply bypassing ensures low-noise, low-distortion performance. Place a  $0.1\mu$ F ceramic capacitor from V<sub>DD</sub> to PGND. Add additional bulk capacitance as required by the application. Locate the bypass capacitor as close to the device as possible.

### **Piezoelectric Speaker Driver**

Low-profile piezoelectric speakers can provide quality sound for portable electronics. However, piezoelectric speakers typically require large voltage swings (>8VP-P) across the speaker element to produce audible sound pressure levels. The MAX9711 can be configured to drive a piezoelectric speaker with up to 10VP-P while operating from a single 5V supply.

Figure 2 shows the THD+N of the MAX9711 driving a piezoelectric speaker. Note that as frequency increases, the THD+N increases. This is due to the capacitive nature of the piezoelectric speaker; as frequency increases, the speaker impedance decreases, resulting in a larger current draw from the amplifier.



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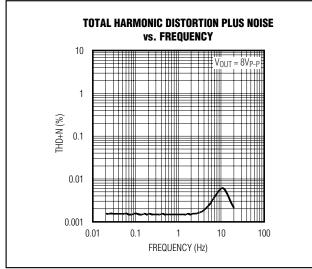


Figure 2. MAX9711 Piezoelectric Speaker Driver THD+N vs. Frequency

The capacitive nature of the piezoelectric speaker may cause the MAX9711 to become unstable. A simple inductor/resistor network in series with the speaker isolates the speaker capacitance from the driver and ensures that the device output sees a resistive load of about  $10\Omega$  at high frequency, thereby maintaining stability (Figure 3).

### Layout and Grounding

Good PC board layout is essential for optimizing performance. Use large traces for the power-supply inputs and amplifier outputs to minimize losses due to parasitic trace resistance and route heat away from the device. Good grounding improves audio performance, minimizes crosstalk between channels, and prevents any digital switching noise from coupling into the audio signal.

The MAX9710/MAX9711 thin QFN and TSSOP-EP packages feature exposed thermal pads on their undersides. This pad lowers the thermal resistance of the package by providing a direct-heat conduction path from the die to the printed circuit board. Connect the exposed pad to the ground plane using multiple vias, if required. For optimum performance, connect to the ground planes as shown in Figure 4.

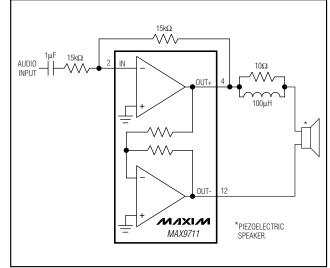


Figure 3. Isolation Network for Driving a Piezoelectric Speaker

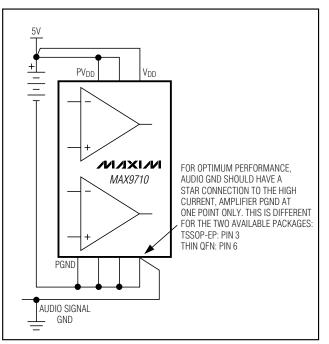
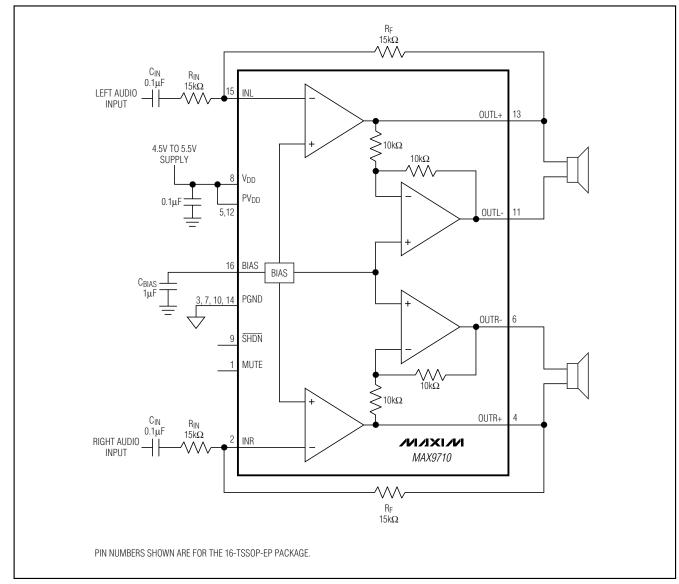


Figure 4. MAX9710 Audio Ground Connection

### M/IXI/M

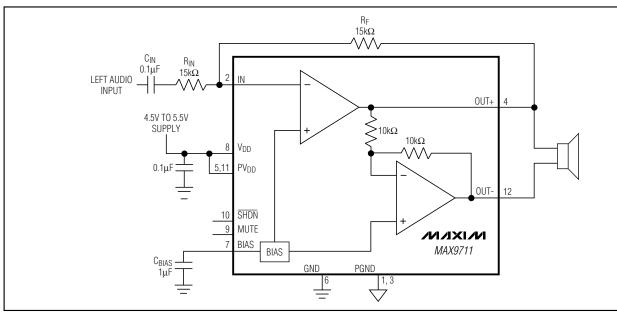
**MAX9710/MAX971** 

**Functional Diagrams** 

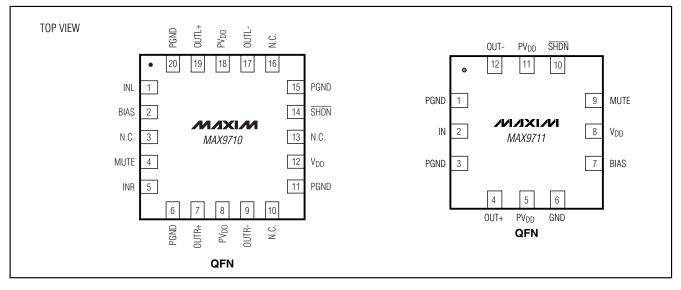


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# Functional Diagrams (continued)



# \_Pin Configurations (continued)



MAX9710/MAX9711

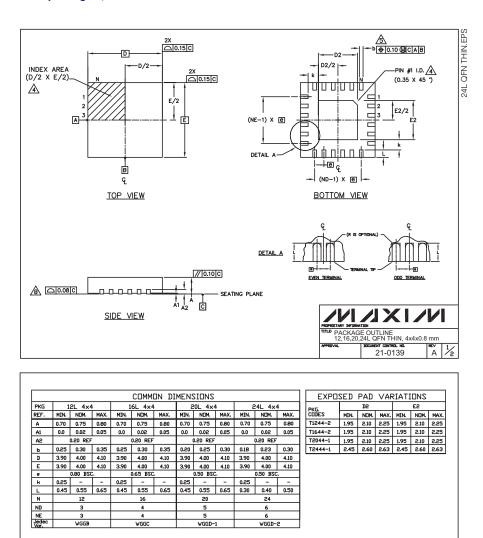
System Diagram MAX9710/MAX9711 V<sub>DD</sub> (5V) 0.1µF 15k $\Omega$ WV  $0.1 \mu F$   $15 k \Omega$ INR  $\Lambda \Lambda \Lambda$ OUTR+ V<sub>DD</sub> PV<sub>DD</sub> OUTR-0.1µF MUTE AUX\_IN 1µF MAX9710 ┥┝ OUT 1μF /VI/IXI/VI -SHDN MAX4060 0.1μF 15kΩ OUTL-CODEC OUTL+ BIAS ┥┝  $\sim$ INL  $15k\Omega$  $2.2k\Omega \ge$  $\sim$ Vcc 0.1µF ┥┝ IN+  $\leq$  100k $\Omega$ Q - V<sub>DD</sub>/2 IN-0.1µF MAX961  $\sim$ Q IN+ 100k $\Omega$ 0.1µF SHDNL SHDNR /VI/IXI/VI 1μF MAX4411 OUTL INL **A** <u>\_\_\_</u> V<sub>CC</sub> (3.3V) 1μF OUTR INR PVss SVSS Vcc C1P CIN 1μF 1μF 1μF

# Chip Information

MAX9710 TRANSISTOR COUNT: 1172 MAX9711 TRANSISTOR COUNT: 780 PROCESS: BICMOS

# Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to www.maxim-ic.com/packages.)



NOTES:

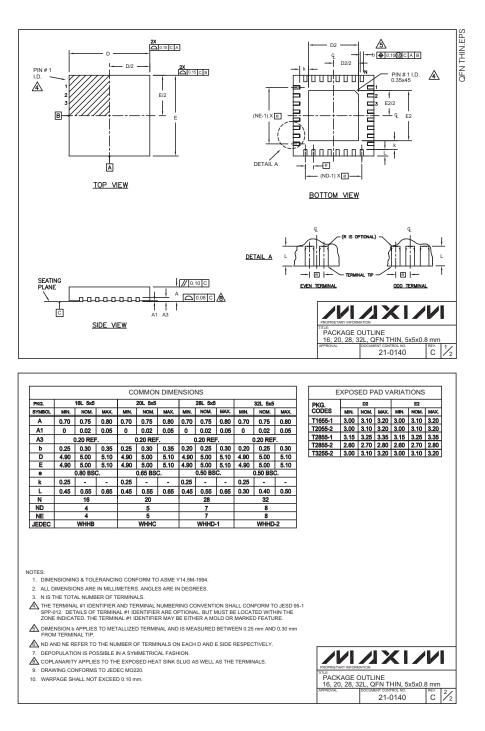
- DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.5M-1994. ALL DIMENSIONS ARE IN MILLIMETERS, ANGLES ARE IN DEGREES.
- N IS THE TOTAL NUMBER OF TERMINALS.
- THE TERMINAL #1 IDENTIFIER AND TERMINAL NUMBERING CONVENTION SHALL CONFORM TO JESO 95-1 SPP-012, DETAILS OF TERMINAL #1 IDENTIFIER ARE OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE TERMINAL #1 IDENTIFIER MAY BE ETHER A MOLD OF MARKED FAUTURE.
- DIMENSION & APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.25 mm AND 0.30 mm
- A ND AND NE REFER TO THE NUMBER OF TERMINALS ON EACH D AND E SIDE RESPECTIVELY.
- DEPOPULATION IS POSSIBLE IN A SYMMETRICAL FASHION.
- A COPLANARITY APPLIES TO THE EXPOSED HEAT SINK SLUG AS WELL AS THE TERMINALS.
- DRAWING CONFORMS TO JEDEC M0220.



///XI//

# Package Information (continued)

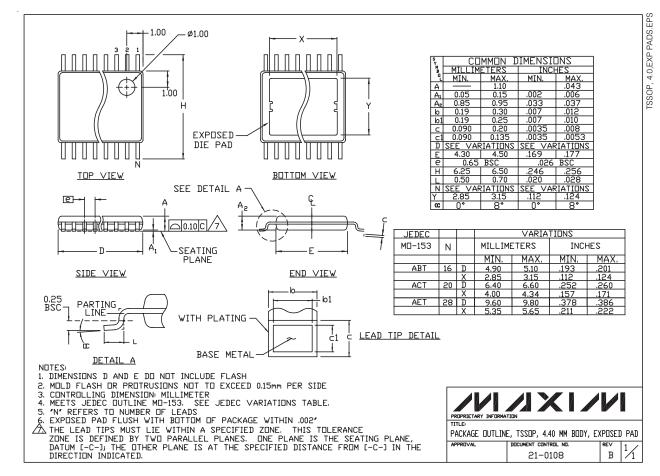
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# Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to <u>www.maxim-ic.com/packages</u>.)



MAX9710/MAX971

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